



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



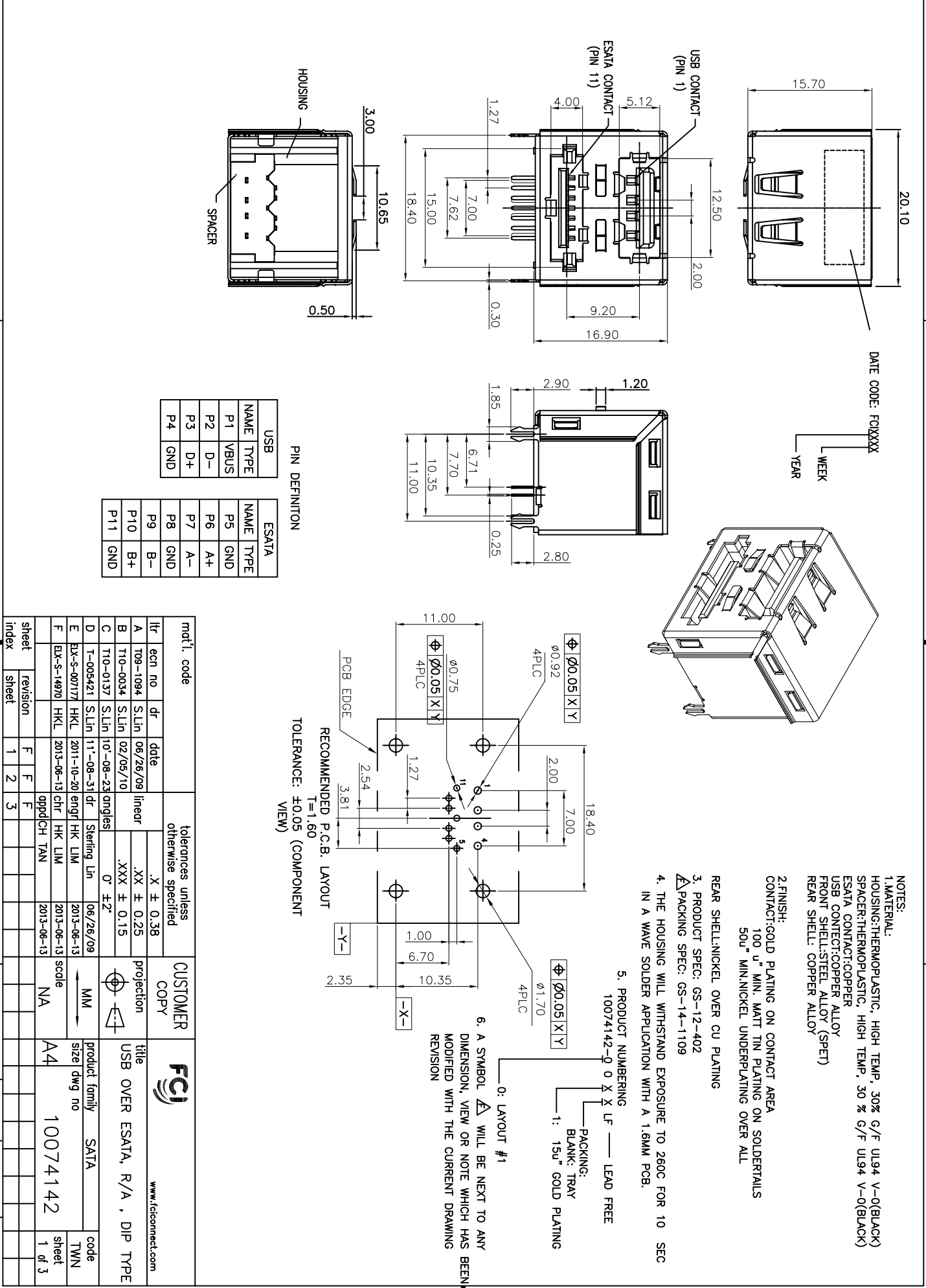
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DATE CODE: F0XXXX  
 WEEK  
 YEAR

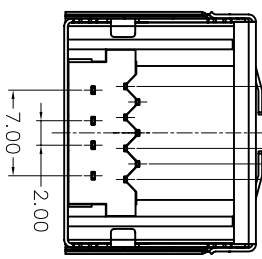
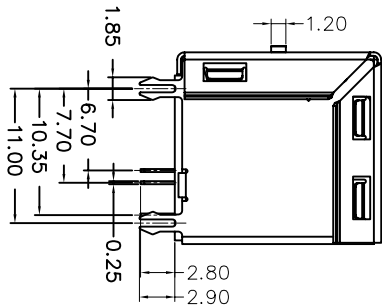
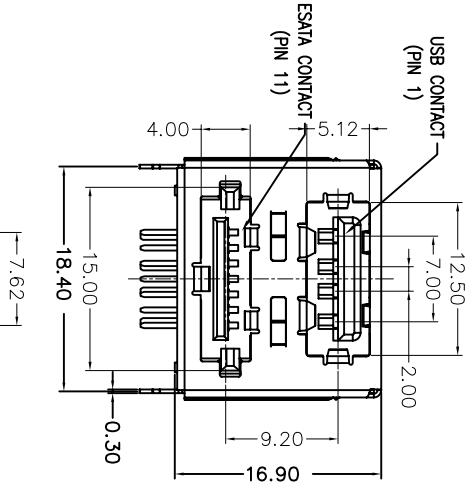
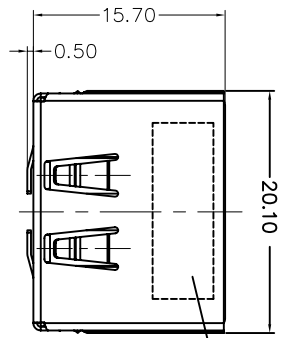
PIN DEFINITION

USB	NAME	TYPE	ESATA	NAME	TYPE
P1	VBUS	D-	P5	GND	B+
P2	D-	D+	P6	A+	A-
P3	D+	A-	P7	A-	GND
P4	GND	B-	P8	GND	B-
			P9	B-	
			P10	B+	
			P11	GND	

RECOMMENDED P.C.B. LAYOUT  
 T=1.60  
 TOLERANCE: ±0.05 (COMPONENT VIEW)

- NOTES:
1. MATERIAL: HOUSING: THERMOPLASTIC, HIGH TEMP, 30% G/F U.94 V-0 (BLACK) SPACER: THERMOPLASTIC, HIGH TEMP, 30% G/F U.94 V-0 (BLACK) ESATA CONTACT: COPPER USB CONTACT: COPPER FRONT SHELL: STEEL ALLOY (SPET) REAR SHELL: COPPER ALLOY
  2. FINISH: CONTACT: GOLD PLATING ON CONTACT AREA 100 u" MIN. MATT TIN PLATING ON SOLDER TAILS 50 u" MIN. NICKEL UNDERPLATING OVER ALL
  3. PRODUCT SPEC: GS-12-402
  4. THE HOUSING WILL WITHSTAND EXPOSURE TO 260C FOR 10 SEC IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB.
  5. PRODUCT NUMBERING 10074142-0 0 X X LF — LEAD FREE

mat'l. code	ecrn no	dr	ddte	tolerances unless otherwise specified	CUSTOMER COPY	title	product family	code
A	109-1094	S.Lin	06/26/09	.XX ± 0.25	projection	USB OVER ESATA, R/A, DIP TYPE	SATA	TWN
B	110-0034	S.Lin	02/05/10	.XXX ± 0.15				sheet
C	110-0137	S.Lin	10'-08-23 angles	0' ±2'				1 of 3
D	T-005421	S.Lin	11'-08-31 dr					
E	EX-S-007171	HKL	2013-06-13					
F	EX-S-14970	HKL	2013-06-13					

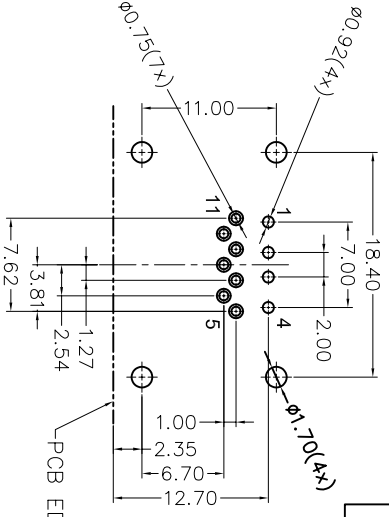
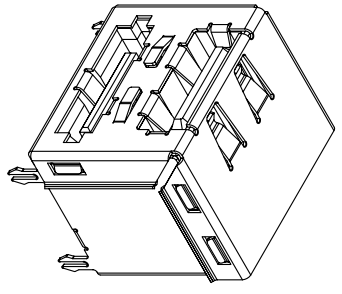


USB	
NAME	TYPE
P1	VBUS
P2	D-
P3	D+
P4	GND

E-SATA	
NAME	TYPE
P5	GND
P6	A+
P7	A-
P8	GND
P9	B-
P10	B+
P11	GND

< PIN DEFINITION >

DATE CODE: FCXXXX  
YEAR  
WEEK

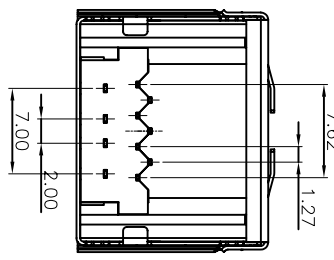
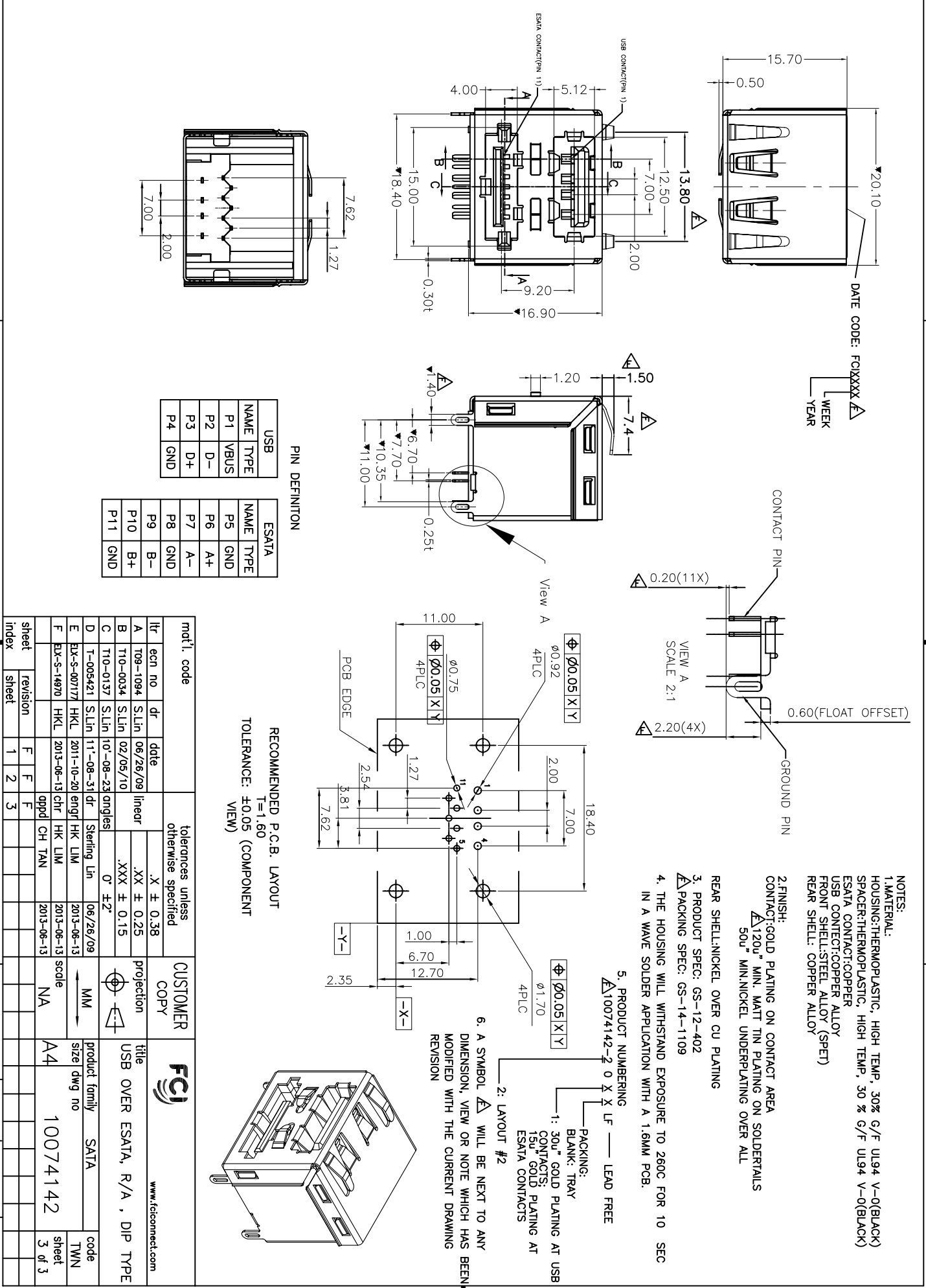


RECOMMENDED PCB LAYOUT(T=1.60mm)  
TOLERANCE: ±0.05

- NOTES:
1. MATERIAL:  
HOUSING: THERMOPLASTIC, HIGH TEMP, 30% G/F UL94 V-0(BLACK)  
SPACER: THERMOPLASTIC, HIGH TEMP, 30% G/F UL94 V-0(BLACK)  
ESATA CONTACT: COPPER  
USB CONTACT: COPPER ALLOY  
FRONT SHELL: STEEL ALLOY (SPET)  
REAR SHELL: COPPER ALLOY
  2. FINISH:  
CONTACT: GOLD PLATING ON CONTACT AREA  
100 μ" MIN. MATT TIN PLATING ON SOLDERTAILS  
500 μ" MIN. NICKEL UNDERPLATING OVER ALL
  3. PRODUCT SPEC: GS-12-402  
PACKING SPEC: GS-14-1109
  4. THE HOUSING WILL WITHSTAND EXPOSURE TO 280C FOR 10 SEC IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB.
  5. PRODUCT NUMBERING  
10074142-1 0 X X LF — LEAD FREE

- PACKING: BLANK: TRAY  
1. Δ30U" GOLD PLATING AT USB CONTACTS  
15U" GOLD PLATING AT ESATA CONTACTS
- 1: LAYOUT #2
6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

mat'l. code		tolerances unless otherwise specified		CUSTOMER COPY	FCI	title	product family	code
ltr	ecrn no	dr	ddte	lineor	projection	MM	SATA	code
A	109-1094	S.Lin	06/26/09	.XX ± 0.38	11'-08-31	dr	Sterling Lin	06/26/09
B	110-0034	S.Lin	02/05/10	.XXX ± 0.15	10'-08-23	angles	0 ±2°	
C	110-0137	S.Lin	10'-08-23					
D	T-005421	S.Lin	11'-08-31	dr				
E	EX-S-007171	HKL	2013-06-13	engr	HK	LIM	2013-06-13	
F	EX-S-14970	HKL	2013-06-13	chr	HK	LIM	2013-06-13	
sheet	revision	F	F	F	pppd	CH	TAN	2013-06-13
index	sheet	1	2	3				

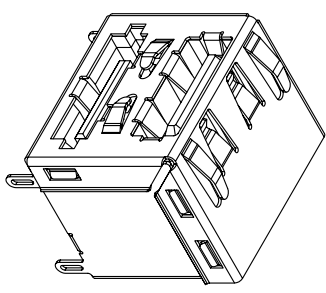


**PIN DEFINITION**

USB	ESATA
NAME	NAME
TYPE	TYPE
P1	P5
VBUS	GND
P2	P6
D-	A+
P3	P7
D+	A-
P4	P8
GND	GND
	P9
	B-
	P10
	B+
	P11
	GND

mat'l. code	ecrn no	dr	ddte	tolerances unless otherwise specified	CUSTOMER COPY	projection	title
	A	T09-1094	S.Lin 06/26/09	.X ± 0.38			USB OVER ESATA, R/A, DIP TYPE
	B	T10-0034	S.Lin 02/05/10	.XX ± 0.25			
	C	T10-0137	S.Lin 10'-08-23 angles	.XXX ± 0.15			
	D	T-005421	S.Lin 11'-08-31 dr	0' ±2			
	E	EX-S-007171	HKL 2013-06-13				
	F	EX-S-14970	HKL 2013-06-13				

RECOMMENDED P.C.B. LAYOUT  
T=1.60  
TOLERANCE: ±0.05 (COMPONENT VIEW)



- NOTES:**
1. MATERIAL: HOUSING: THERMOPLASTIC, HIGH TEMP, 30% G/F U.94 V-0(BLACK) SPACER: THERMOPLASTIC, HIGH TEMP, 30% G/F U.94 V-0(BLACK) ESATA CONTACT: COPPER USB CONTACT: COPPER FRONT SHELL: STEEL ALLOY (SPET) REAR SHELL: COPPER ALLOY
  2. FINISH: CONTACT: GOLD PLATING ON CONTACT AREA Δ120μ" MIN. MATT TIN PLATING ON SOLDER TAILS 50μ" MIN. NICKEL UNDERPLATING OVER ALL
  3. PRODUCT SPEC: GS-12-402
  4. THE HOUSING WILL WITHSTAND EXPOSURE TO 260C FOR 10 SEC IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB.
  5. PRODUCT NUMBERING Δ10074142-2 0 X X X LF — LEAD FREE
  6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

PACKING: TRAY  
1: 30μ" GOLD PLATING AT USB CONTACTS 15μ" GOLD PLATING AT ESATA CONTACTS  
2: LAYOUT #2